

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 04-340746
 (43)Date of publication of application : 27.11.1992

(51)Int.CI. H01L 21/78
 H01L 21/68

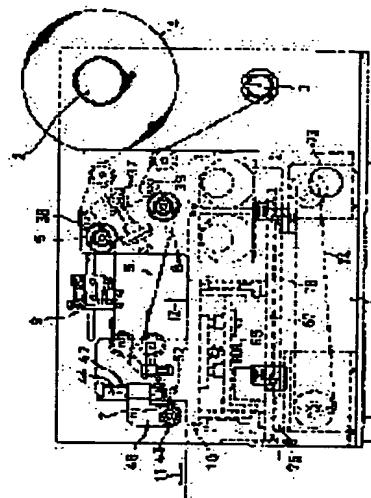
(21)Application number : 03-112833 (71)Applicant : LINTEC CORP
 (22)Date of filing : 17.05.1991 (72)Inventor : KOBAYASHI KENJI
 SAITO HIROSHI
 KAWARADA KENJI
 TSUJIMOTO MASAKI

(54) ADHESIVE TAPE STICKING DEVICE

(57)Abstract:

PURPOSE: To obtain an inexpensive adhesive tape sticking device which has such a simple constitution that a semiconductor wafer can be manually set to a ring frame and no special apparatus is required for giving tension to an adhesive tape.

CONSTITUTION: A peel plate 7 which peels an adhesive tape from a release frame 5 and a press roller 43 which is provided near the plate 7 and makes free rotation when the roller 43 is moved at its upper position and driven rotation when the roller 43 is moved at its lower position are provided and a table 56 mounted with a semiconductor wafer and ring frame is provided in such a state that the table 56 can freely make reciprocating motions between a position below the roller 43 and another position separated from the position and the table 56 can be brought into contact and separated from the roller 43. The release film 5 is driven by means of a torque motor and a tension roller 6 which works in conjunction with a pinch roller and a drive roller 8 give tension to the film.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision]

BEST AVAILABLE COPY

of rejection]

[Date of requesting appeal against examiner's
decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office